



PMBFJ108; PMBFJ109; PMBFJ110

N-channel junction FETs

Rev. 4 — 20 September 2011

Product data sheet

1. Product profile

1.1 General description

Symmetrical N-channel junction FETs in a SOT23 package.

1.2 Features and benefits

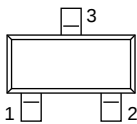
- High-speed switching
- Interchangeability of drain and source connections
- Low $R_{DS(on)}$ at zero gate voltage ($< 8 \Omega$ for PMBFJ108).

1.3 Applications

- Analog switches
- Choppers and commutators
- Audio amplifiers.

2. Pinning information

Table 1. Pinning

Pin	Description ^[1]	Simplified outline	Symbol
1	drain		 sym053
2	source		
3	gate		

[1] Drain and source are interchangeable.

3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
PMBFJ108	-	plastic surface mounted package; 3 leads	SOT23
PMBFJ109			
PMBFJ110			

4. Marking

Table 3. Marking

Type number	Marking code ^[1]
PMBFJ108	38*
PMBFJ109	39*
PMBFJ110	40*

[1] * = p: Made in Hong Kong

* = t: Made in Malaysia

* = W: Made in China

5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)		-	± 25	V
V_{GSO}	gate-source voltage		-	-25	V
V_{GDO}	gate-drain voltage		-	-25	V
I_G	forward gate current (DC)		-	50	mA
P_{tot}	total power dissipation	$T_{amb} = 25\text{ °C}$	^[1] -	250	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-	150	°C

[1] Mounted on an FR4 printed-circuit board.

6. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient		^[1] 500	K/W

[1] Mounted on an FR4 printed-circuit board.

7. Static characteristics

Table 6. Static characteristics

$T_j = 25\text{ }^{\circ}\text{C}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{GSS}	gate-source leakage current	$V_{GS} = -15\text{ V}$; $V_{DS} = 0\text{ V}$	-	-	-3	nA
I_{DSX}	drain-source cut-off current	$V_{GS} = -10\text{ V}$; $V_{DS} = 5\text{ V}$	-	-	3	nA
I_{DSS}	drain-source leakage current					
	PMBFJ108	$V_{GS} = 0\text{ V}$; $V_{DS} = 15\text{ V}$	80	-	-	mA
	PMBFJ109	$V_{GS} = 0\text{ V}$; $V_{DS} = 15\text{ V}$	40	-	-	mA
	PMBFJ110	$V_{GS} = 0\text{ V}$; $V_{DS} = 15\text{ V}$	10	-	-	mA
$V_{(BR)GSS}$	gate-source breakdown voltage	$I_G = -1\text{ }\mu\text{A}$; $V_{DS} = 0\text{ V}$	-	-	-25	V
V_{GSoff}	gate-source cut-off voltage					
	PMBFJ108	$I_D = 1\text{ }\mu\text{A}$; $V_{DS} = 5\text{ V}$	-10	-	-3	V
	PMBFJ109	$I_D = 1\text{ }\mu\text{A}$; $V_{DS} = 5\text{ V}$	-6	-	-2	V
	PMBFJ110	$I_D = 1\text{ }\mu\text{A}$; $V_{DS} = 5\text{ V}$	-4	-	-0.5	V
R_{DSon}	drain-source on-state resistance					
	PMBFJ108	$V_{GS} = 0\text{ V}$; $V_{DS} = 0.1\text{ V}$	-	-	8	Ω
	PMBFJ109	$V_{GS} = 0\text{ V}$; $V_{DS} = 0.1\text{ V}$	-	-	12	Ω
	PMBFJ110	$V_{GS} = 0\text{ V}$; $V_{DS} = 0.1\text{ V}$	-	-	18	Ω

8. Dynamic characteristics

Table 7. Dynamic characteristics

$T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C_{iss}	input capacitance	$V_{DS} = 0\text{ V}$; $V_{GS} = -10\text{ V}$; $f = 1\text{ MHz}$	-	15	30	pF
		$V_{DS} = 0\text{ V}$; $V_{GS} = 0\text{ V}$; $f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	-	50	85	pF
C_{rss}	feedback capacitance	$V_{DS} = 0\text{ V}$; $V_{GS} = -10\text{ V}$; $f = 1\text{ MHz}$	-	8	15	pF
Switching times (see Figure 2)						
t_d	delay time		[1]	-	2	ns
t_{on}	turn-on time		[1]	-	4	ns
t_s	storage time		[1]	-	4	ns
t_{off}	turn-off time		[1]	-	6	ns

[1] Test conditions for switching times are as follows:

$V_{DD} = 1.5\text{ V}$, $V_{GS} = 0\text{ V}$ to V_{GSoff} (all types);

$V_{GSoff} = -12\text{ V}$, $R_L = 100\text{ }\Omega$ (PMBFJ108);

$V_{GSoff} = -7\text{ V}$, $R_L = 100\text{ }\Omega$ (PMBFJ109);

$V_{GSoff} = -5\text{ V}$, $R_L = 100\text{ }\Omega$ (PMBFJ110).

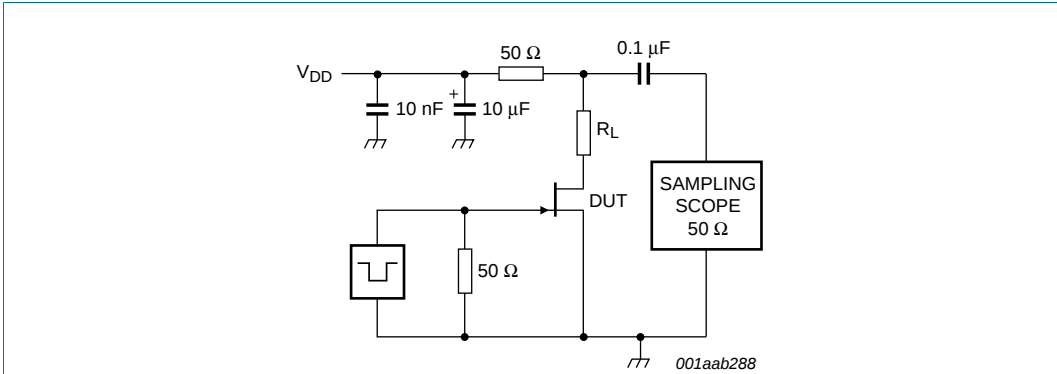


Fig 1. Switching circuit.

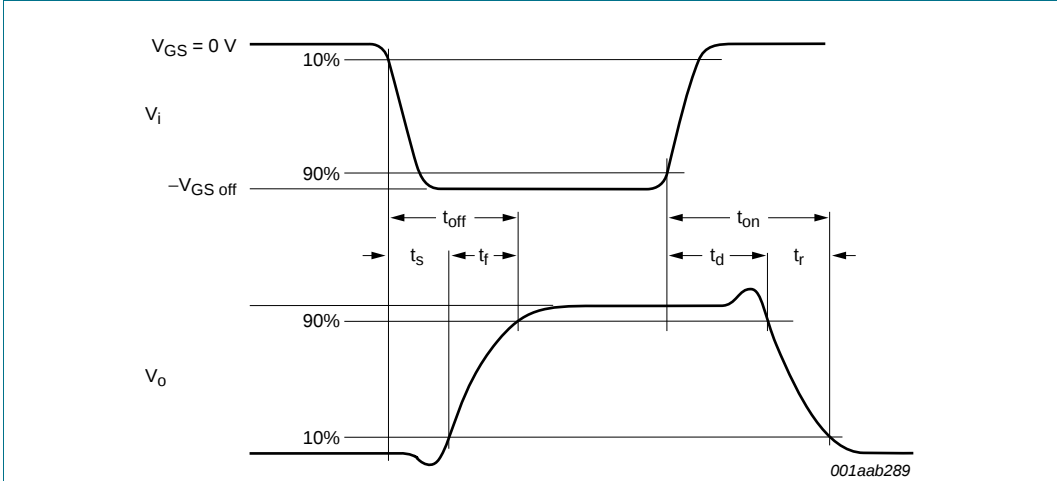


Fig 2. Input and output waveforms.

9. Package outline

Plastic surface-mounted package; 3 leadsSOT23

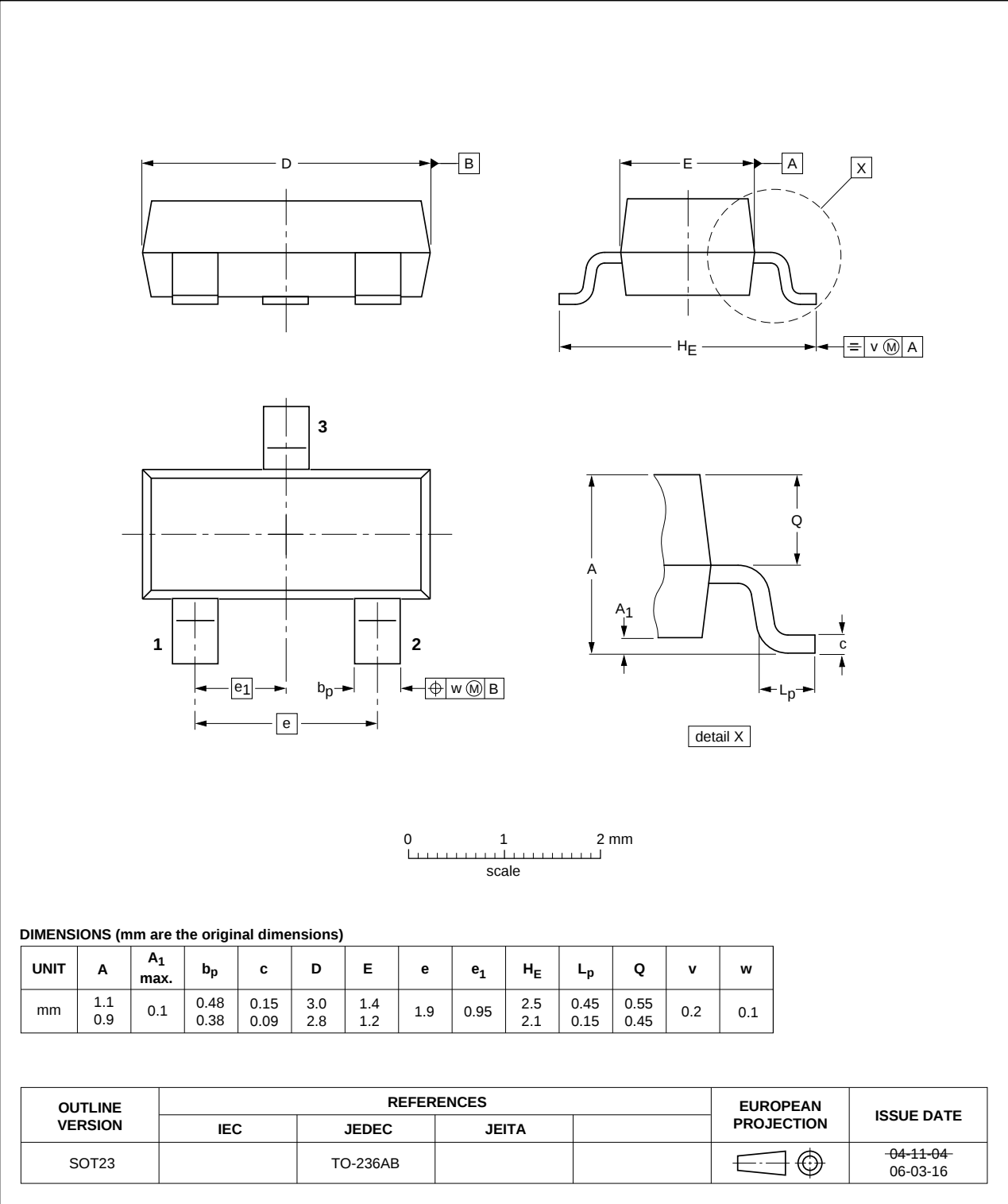


Fig 3. Package outline.

10. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMBFJ108_109_110 v.4	20110920	Product data sheet	-	PMBFJ108_109_110 v.3
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Package outline drawings have been updated to the latest version.			
PMBFJ108_109_110 v.3 (9397 750 13401)	20040804	Product data sheet	-	PMBFJ108_109_110_CNV v.2
PMBFJ108_109_110_CNV v.2	19971201	Product specification	-	-

11. Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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